

Description

The RD3P200SNFRATL uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



TO-252-2L

General Features

 $V_{DS} = 100V I_{D} = 30A$

 $R_{DS(ON)}$ < 48m Ω @ V_{GS} =10V



Battery protection

Load switch N-Channel MOSFET

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
RD3P200SNFRATL	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	100	V	
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20		
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	Α	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	13	А	
Ірм	Pulsed Drain Current ²	80	Α	
EAS	Single Pulse Avalanche Energy ³	gy ³ 30		
P _D @T _C =25°C	Total Power Dissipation ⁴	42	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R _θ JC	Thermal Resistance Junction-Case ¹	3.6	°C/W	

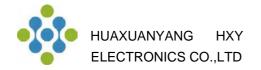
N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic		1	l		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Charac	cteristics					
$V_{GS(th)}$	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	1.0	1.5	2.2	V
	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =10A	-	37	48	mΩ
$R_{DS(on)}$	note3	V _{GS} =4.5V, I _D =6A	-	39	55	mΩ
Dynamic (Characteristics					
C _{iss}	Input Capacitance	\\ O5\\\\	-	1964	-	pF
Coss	Output Capacitance	V_{DS} =25V, V_{GS} =0V, f=1.0MHz	-	90	-	pF
C _{rss}	Reverse Transfer Capacitance	1-1.UIVITZ	-	74	-	рF
Qg	Total Gate Charge	V _{DS} =80V, I _D =20A,	-	20	-	nC
Q_gs	Gate-Source Charge		-	3.1	-	nC
Q_gd	Gate-Drain("Miller") Charge	V _{GS} =4.5V	-	14	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	11	-	ns
t _r	Turn-on Rise Time	V _{DS} =80V, I _D =20A,	-	91	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_{G} =3.1 Ω , V_{GS} =4.5 V	-	40	-	ns
t _f	Turn-off Fall Time		-	71	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings				
ı	Maximum Continuous Drain to Source	Maximum Continuous Drain to Source Diode Forward			27	٨
Is	Current		-	-	27	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	80	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =20A	-	_	1.2	V
trr	Body Diode Reverse Recovery Time	I -20A	-	64	-	ns
Qrr	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=100A/μs	-	152	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition : T_J=25 $^{\circ}\text{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω ,I_AS= 11A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

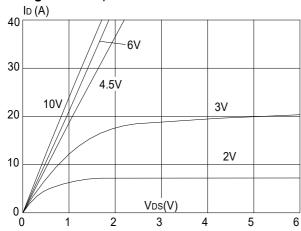


Figure 2: Typical Transfer Characteristics

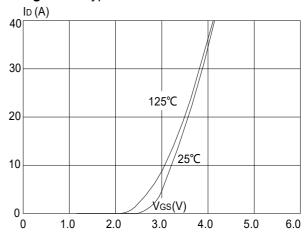


Figure 3:On-resistance vs. Drain Current

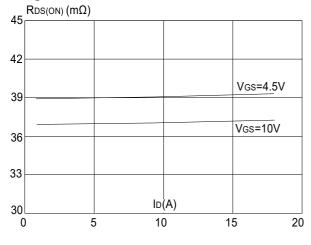


Figure 4: Body Diode Characteristics

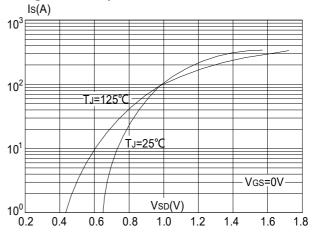


Figure 5: Gate Charge Characteristics

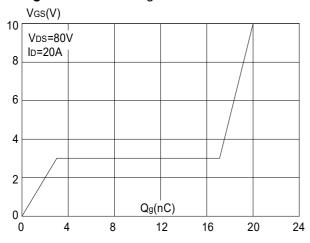


Figure 6: Capacitance Characteristics

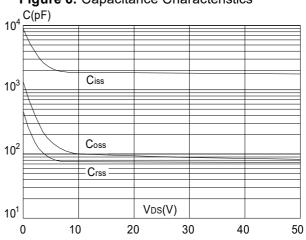




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

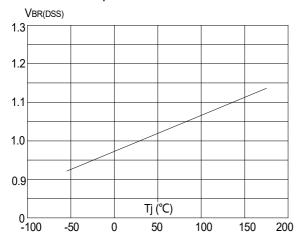


Figure 9: Maximum Safe Operating Area

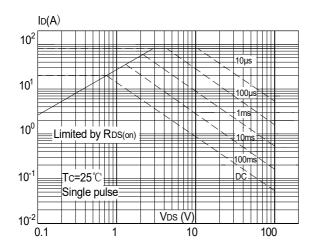


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

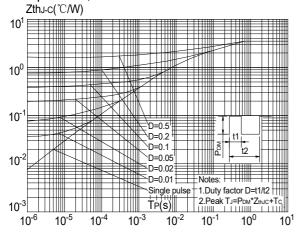


Figure 8: Normalized on Resistance vs. Junction Temperature

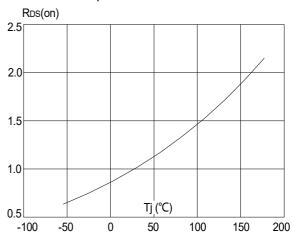
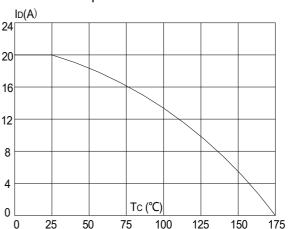
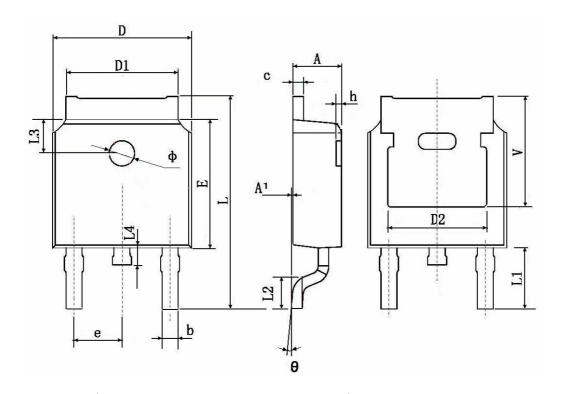


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



N-Channel Enhancement Mode MOSFET

TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		

RD3P200SNFRATL

N-Channel Enhancement Mode MOSFET

Attention

- Any and all HUA XUAN YANG ELECTRONICS products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your HUA XUAN YANG ELECTRONICS representative nearest you before using any HUA XUAN YANG ELECTRONICS products described or contained herein in such applications.
- HUA XUAN YANG ELECTRONICS assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein.
- Specifications of any and all HUA XUAN YANG ELECTRONICS products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- HUA XUAN YANG ELECTRONICS CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all HUA XUAN YANG ELECTRONICS products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of HUA XUAN YANG ELECTRONICS CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production.

 HUA XUAN YANG ELECTRONICS believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the HUA XUAN YANG ELECTRONICS product that you intend to use.